

# BYC20-600

Rectifier diode, hyperfast

Rev. 01 — 28 November 2007

Product data sheet

## 1. Product profile

### 1.1 General description

Hyperfast, epitaxial rectifier diode in a SOD59 (2-lead TO-220AC) plastic package.

### 1.2 Features

- Extremely fast switching
- Reduces switching loss in associated MOSFET
- Low thermal resistance
- Low reverse recovery current

### 1.3 Applications

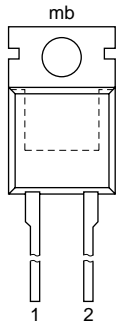

- Half-bridge or full-bridge switched-mode power supplies
- Half-bridge lighting ballasts
- Continuous Current Mode (CCM) Power Factor Correction (PFC)

### 1.4 Quick reference data

- $V_{RRM} \leq 600$  V
- $V_F = 1.54$  V (typ)
- $I_{F(AV)} \leq 20$  A
- $t_{rr} = 19$  ns (typ)

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode (k)		 001aaa020
2	anode (a)		
mb	mounting base; cathode		

SOD59 (2-lead TO-220AC)

### 3. Ordering information

**Table 2. Ordering information**

Type number	Package		Version
	Name	Description	
BYC20-600	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

### 4. Limiting values

**Table 3. Limiting values**

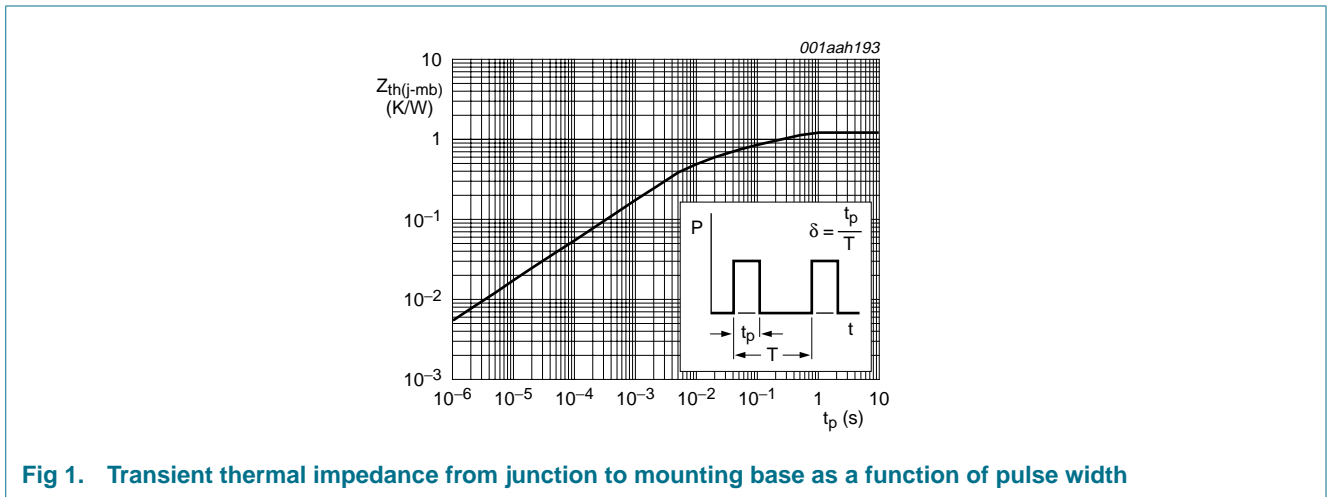
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	square waveform; $\delta = 1.0$ ; $T_{mb} \leq 100$ °C	-	500	V
$I_{F(AV)}$	average forward current	square waveform; $\delta = 0.5$ ; $T_{mb} \leq 93$ °C	-	20	A
$I_{FRM}$	repetitive peak forward current	square waveform; $\delta = 0.5$ ; $T_{mb} \leq 93$ °C; $t_p = 25$ $\mu$ s;	-	40	A
$I_{FSM}$	non-repetitive peak forward current	$t = 10$ ms; sinusoidal waveform	-	250	A
		$t = 8.3$ ms; sinusoidal waveform	-	274	A
$T_{stg}$	storage temperature		-40	+150	°C
$T_j$	junction temperature		-	150	°C

**5. Thermal characteristics**

**Table 4. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; see <a href="#">Figure 1</a>	-	-	1.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W



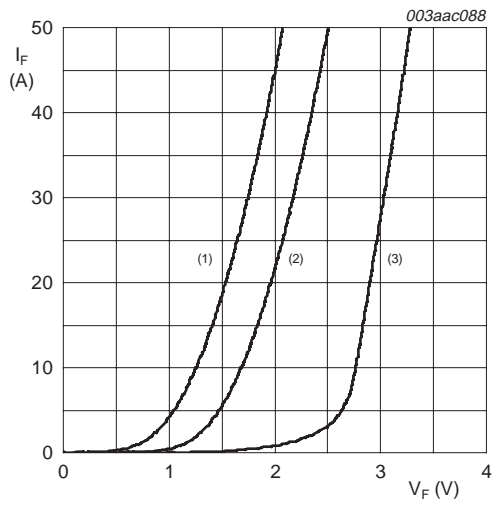
**Fig 1. Transient thermal impedance from junction to mounting base as a function of pulse width**

## 6. Characteristics

**Table 5. Characteristics**

$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 20\text{ A}$ ; $T_j = 150\text{ °C}$ ; see <a href="#">Figure 2</a>	-	1.54	1.97	V
		$I_F = 40\text{ A}$ ; $T_j = 150\text{ °C}$ ; see <a href="#">Figure 2</a>	-	1.95	2.34	V
		$I_F = 20\text{ A}$ ; see <a href="#">Figure 2</a>	-	1.89	2.9	V
$I_R$	reverse current	$V_R = 600\text{ V}$	-	16	200	$\mu\text{A}$
		$V_R = 500\text{ V}$ ; $T_j = 100\text{ °C}$	-	1.6	3.0	mA
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ to $V_R = 30\text{ V}$ ; $dI_F/dt = 50\text{ A}/\mu\text{s}$ ; see <a href="#">Figure 3</a>	-	35	55	ns
		$I_F = 20\text{ A}$ to $V_R = 400\text{ V}$ ; $dI_F/dt = 500\text{ A}/\mu\text{s}$ ; see <a href="#">Figure 3</a>	-			
		$T_j = 25\text{ °C}$	-	19	-	ns
		$T_j = 100\text{ °C}$	-	32	40	ns
$I_{RM}$	peak reverse recovery current	$I_F = 20\text{ A}$ to $V_R = 400\text{ V}$ ; $T_j = 125\text{ °C}$ ; see <a href="#">Figure 3</a>	-			
		$dI_F/dt = 50\text{ A}/\mu\text{s}$	-	3.0	7.5	A
		$dI_F/dt = 500\text{ A}/\mu\text{s}$	-	9.5	12	A
$V_{FR}$	forward recovery voltage	$I_F = 20\text{ A}$ ; $dI_F/dt = 100\text{ A}/\mu\text{s}$ ; see <a href="#">Figure 4</a>	-	8	11	V



- (1)  $T_j = 150\text{ }^\circ\text{C}$ ; typical values
- (2)  $T_j = 150\text{ }^\circ\text{C}$ ; maximum values
- (3)  $T_j = 25\text{ }^\circ\text{C}$ ; maximum values

Fig 2. Forward current as a function of forward voltage

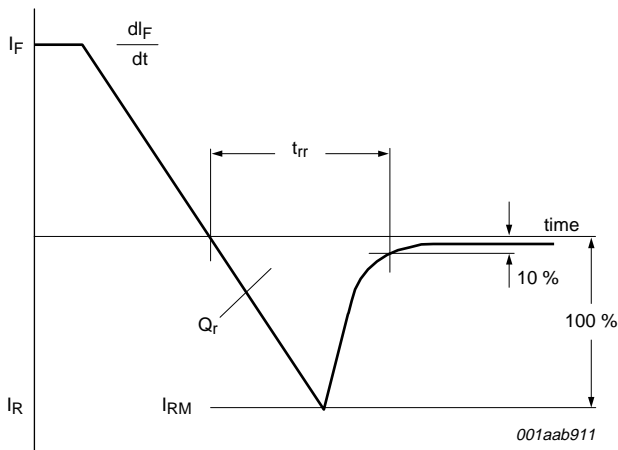


Fig 3. Reverse recovery definitions

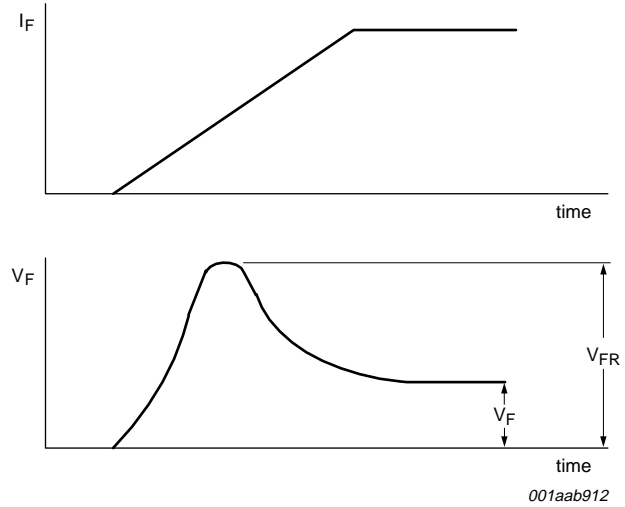
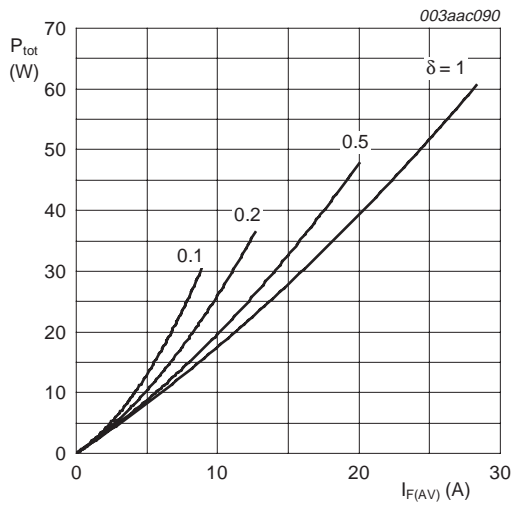
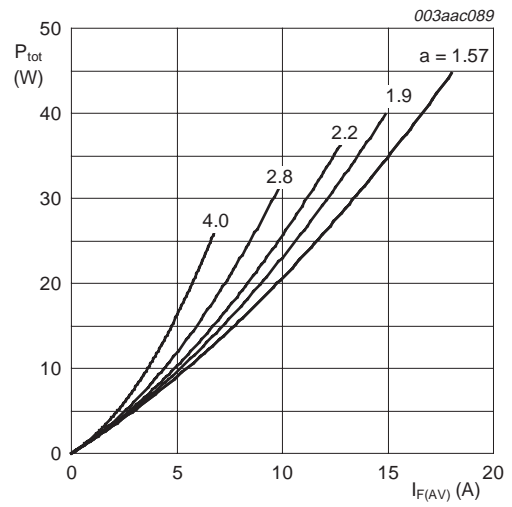


Fig 4. Forward recovery definitions



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

**Fig 5. Forward power dissipation as a function of average forward current; square waveform; maximum values**



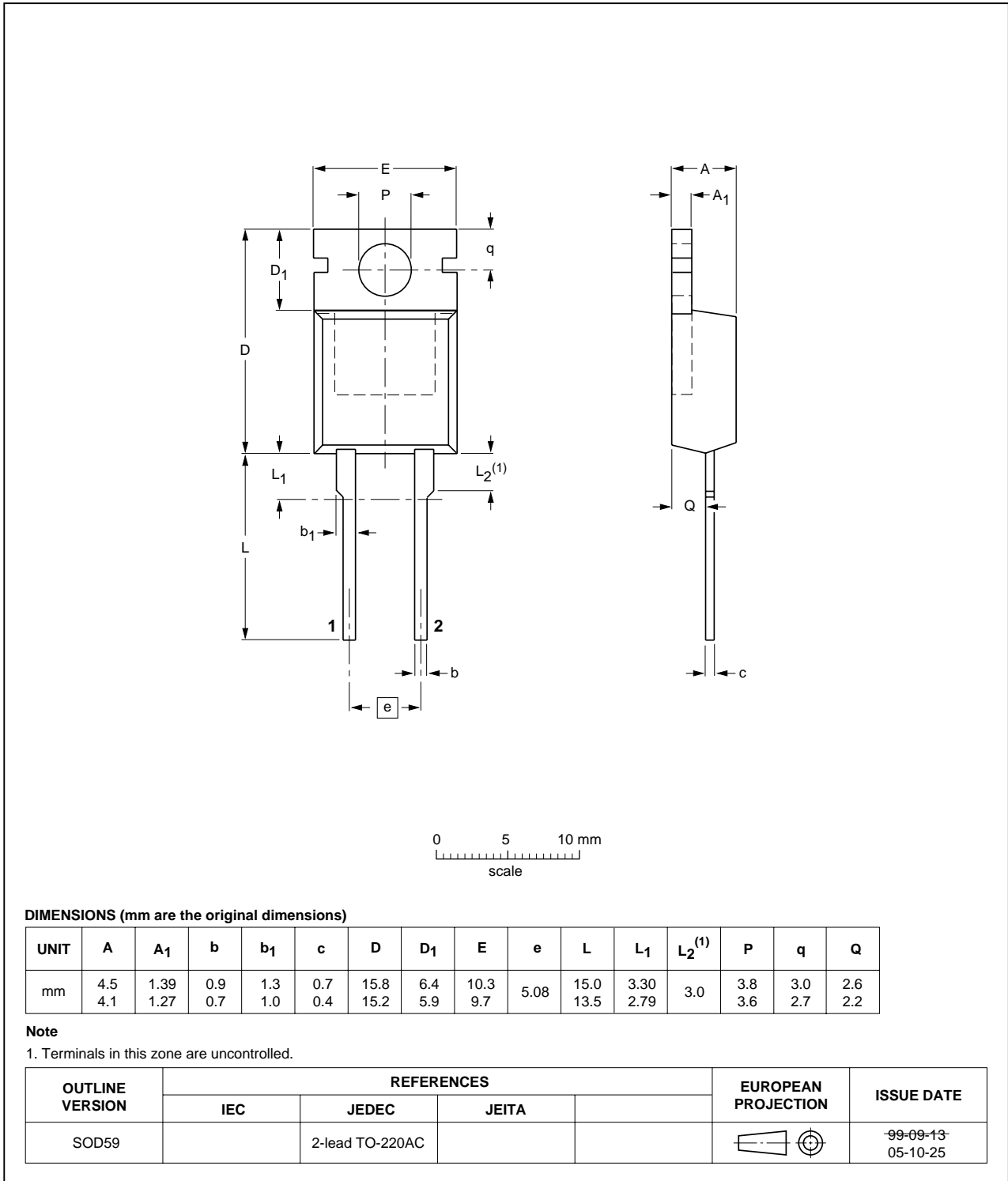
$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

**Fig 6. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

**7. Package outline**

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

SOD59



**Fig 7. Package outline SOD59 (2-lead TO-220AC)**

## 8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYC20-600_1	20071128	Product data sheet	-	-



## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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